

CPD76X-1N5817 Schottky Rectifier Die 1.0 Amp, 20 Volt

The CPD76X-1N5817 is a silicon 1.0 Amp, 20 Volt Schottky rectifier ideal for all types of commercial, industrial, entertainment, and computer applications.

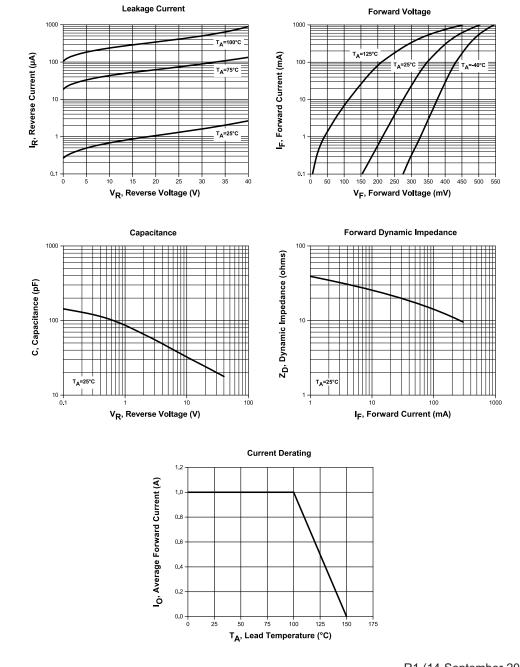
	MECHANICA	L SPECIFICAT	IONS:	
ANODE	Die Size		32 x 32 MILS	
	Die Thicknes	s	5.9 MILS	
	Anode Bond	ing Pad Size	27 x 27 MILS	
	Top Side Me	talization	AI – 20,000Å	
	Back Side M	etalization	Au – 9,000Å	
	Scribe Alley	Width	2.36 MILS	
	Wafer Diame	eter	5 INCHES	
	Gross Die Pe	er Wafer	16,276	
BACKSIDE CATHODE R	 			
MAXIMUM RATINGS: (T _A =25°	C)	SYMBOL		UNITS
Peak Repetitive Reverse Voltage		VRRM	20	V
DC Blocking Voltage		VR	20	V
RMS Reverse Voltage		V _{R(RMS)}	14	V
Average Forward Current (T _A =100°C)		IO	1.0	А
Peak Forward Surge Current, tp=8.3ms		IFSM	25	А
Operating and Storage Junction Temperature		T _J , T _{stg}	-65 to +150	°C
ELECTRICAL CHARACTERIS	ΓΙCS : (Τ _Δ =25°C ι	unless otherwise	e)	
SYMBOL TEST CONDITIONS		MIN	MAX	UNITS
I _R V _R =20V			1.0	mA
V _F I _F =0.1A	I _F =0.1A		320	mV
V _F I _F =1.0A	I _F =1.0A		450	mV
	I _F =3.1A		750	mV
V _F I _F =3.1A				

MECHANICAL SPECIFICATIONS:

CPD76X-1N5817 Typical Electrical Characteristics



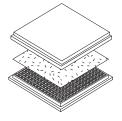
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R1 (14-September 2016)

BARE DIE PACKING OPTIONS



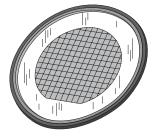


BARE DIE IN TRAY (WAFFLE) PACK

- CT: Singulated die in tray (waffle) pack. (example: CP211-PART NUMBER-CT)
- CM: Singulated die in tray (waffle) pack 100% visually inspected as per MIL-STD-750, (method 2072 transistors, method 2073 diodes). (example: CP211-<u>PART NUMBER</u>-CM)

UNSAWN WAFER

WN: Full wafer, unsawn, 100% tested with reject die inked. (example: CP211-PART NUMBER-WN)



SAWN WAFER ON PLASTIC RING

WR: Full wafer, sawn and mounted on plastic ring, 100% tested with reject die inked. (example: CP211-PART NUMBER-WR)

Please note: Sawn Wafer on Metal Frame (WS) is possible as a special order. Please contact your Central Sales Representative at 631-435-1110.



Visit the Central website for a complete listing of specifications: www.centralsemi.com/bdspecs

www.centralsemi.com

OUTSTANDING SUPPORT AND SUPERIOR SERVICES

PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- Inventory bonding
- · Consolidated shipping options

DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free quick ship samples (2nd day air)
- Online technical data and parametric search
- SPICE models
- Custom electrical curves
- Environmental regulation compliance
- Customer specific screening
- Up-screening capabilities

Special wafer diffusions

· Custom product packing

- PbSn plating options
- Package details
- Application notes
- · Application and design sample kits

Custom bar coding for shipments

Custom product and package development

REQUESTING PRODUCT PLATING

- 1. If requesting Tin/Lead plated devices, add the suffix "TIN/LEAD" to the part number when ordering (example: 2N2222A TIN/LEAD).
- If requesting Lead (Pb) Free plated devices, add the suffix "PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

CONTACT US

Corporate Headquarters & Customer Support Team

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